

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (1.6 EP)
Lead Count	8
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.21E-02	86.2	862000	42.23		422278
Thermosets	Epoxy resin	Proprietary	8.40E-04	6.0	60000	2.94		29393
Thermosets	Phenol resin	Proprietary	8.40E-04	6.0	60000	2.94		29393
Other inorganic materials	Metal Hydroxide	Proprietary	2.10E-04	1.5	15000	0.73		7348
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.3	3000	0.15		1470
Subtotal			1.40 E-02	100.00	1000000	48.99		489881

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.09 E-02	97.50	975000	38.02		380233
Copper & its alloys	Iron	7439-89-6	2.62 E-04	2.35	23500	0.92		9165
Copper & its alloys	Zinc	7440-66-6	1.34 E-05	0.12	1200	0.05		468
Copper & its alloys	Phosphorus	7723-14-0	3.34 E-06	0.03	300	0.01		117
Subtotal			1.11 E-02	100.00	1000000	39.00		389983

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.12 E-05	100.0	1000000	0.04		390

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	7.56 E-04	100.0	1000000	2.65		26454

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.25 E-04	100.0	1000000	0.44		4391

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.44 E-03	100.0	1000000	8.55		85509

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.12 E-05	73.40	734000	0.25		2490
Thermoset	Epoxy Resin	Proprietary	1.78 E-05	18.35	183500	0.06		623
Other organic materials	Metal oxide	Proprietary	2.67 E-06	2.75	27500	0.01		93
Other organic materials	Amine	Proprietary	2.67 E-06	2.75	27500	0.01		93
Other organic materials	Gamma Butyrolactone	Proprietary	2.67 E-06	2.75	27500	0.01		93
Subtotal			9.70 E-05	100.0	1000000	0.34		3392

Package Totals	Weight (g)	Percentage (%)	PPM
	2.86 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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